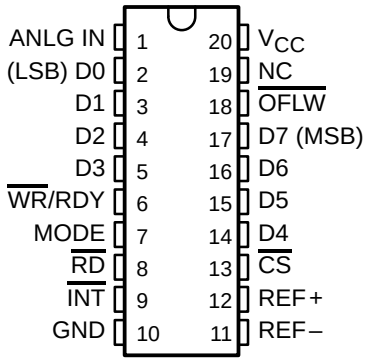
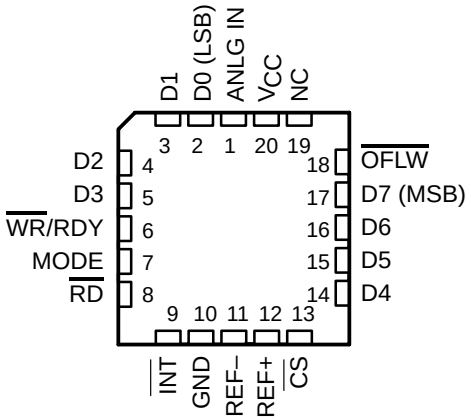
- **Advanced LinCMOS™ Silicon-Gate Technology**
- **8-Bit Resolution**
- **Differential Reference Inputs**
- **Parallel Microprocessor Interface**
- **Conversion and Access Time Over Temperature Range**
  Write-Read Mode . . . 1.18 μs and 1.92 μs
  Read Mode . . . 2.5 μs Max
- **No External Clock or Oscillator Components Required**
- **On-Chip Track-and-Hold**
- **Low Power Consumption . . . 50 mW Typ**
- **Single 5-V Supply**
- **TLC0820B is Direct Replacement for National Semiconductor ADC0820B/BC and Analog Devices AD7820L/C/U; TLC0820A is Direct Replacement for National Semiconductor ADC0820C/CC and Analog Devices AD7820K/B/T**

ALL TYPES . . . DW OR N PACKAGE
TLC0820_M . . . J PACKAGE
(TOP VIEW)



TLC0820_M . . . FK PACKAGE
TLC0820_I, TLC0820_C . . . FN PACKAGE
ADC0820_CI, ADC0820_C . . . FN PACKAGE
{TOP VIEW}



NC – No internal connection

description

The TLC0820A, TLC0820B, ADC0820B, and ADC0820C are Advanced LinCMOS™ 8-bit analog-to-digital converters each consisting of two 4-bit "flash" converters, a 4-bit digital-to-analog converter, a summing (error) amplifier, control logic, and a result latch circuit. The modified "flash" technique allows low-power integrated circuitry to complete an 8-bit conversion in 1.18 μs over temperature. The on-chip track-and-hold circuit has a 100-ns sample window and allows these devices to convert continuous analog signals having slew rates of up to 100 mV/μs without external sampling components. TTL-compatible 3-state output drivers and two modes of operation allow interfacing to a variety of microprocessors. Detailed information on interfacing to most popular microprocessors is readily available from the factory.

The C-suffix devices are characterized for operation from 0°C to 70°C. The I-suffix devices are characterized for operation from –40°C to 85°C. The M-suffix devices are characterized for operation over the full military temperature range of –55°C to 125°C. See Available Options.

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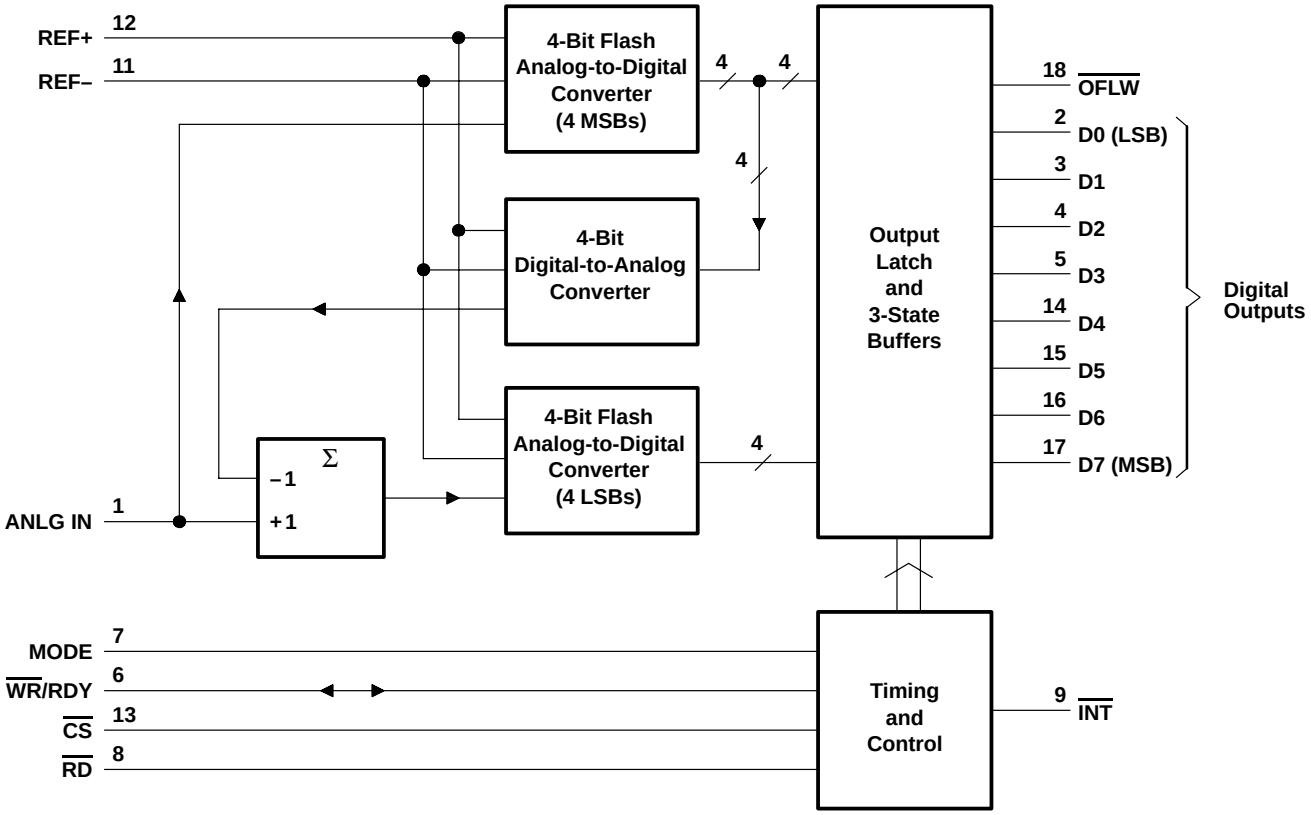
AVAILABLE OPTIONS

SYMBOLIZATION†		OPERATING TEMPERATURE RANGE	TOTAL UNADJUSTED ERROR
DEVICE	PACKAGE SUFFIX		
TLC0820AC	DW, FN, N	0°C to 70°C	±1 LSB
TLC0820AI	DW, FN, N	–40°C to 85°C	±1 LSB
TLC0820AM	DW, FK, J, N	–55°C to 125°C	±1 LSB
TLC0820BC	DW, FN, N	0°C to 70°C	±0.5 LSB
TLC0820BI	DW, FN, N	–40°C to 85°C	±0.5 LSB
TLC0820BM	DW, FK, J, N	–55°C to 125°C	±0.5 LSB
ADC0820BC	DW, FN, N	0°C to 70°C	±0.5 LSB
ADC0820BI	DW, FN, N	–40°C to 85°C	±0.5 LSB
ADC0820CC	DW, FN, N	0°C to 70°C	±1 LSB
ADC0820CI	DW, FN, N	–40°C to 85°C	±1 LSB

† In many instances, these integrated circuits may have both TLC0820 and ADC0820 labeling on the package.

functional block diagram



Terminal Functions

PIN NAME	PIN NO.	DESCRIPTION
ANLG IN	1	Analog input
$\overline{CS}$	13	This input must be low in order for $\overline{RD}$ or $\overline{WD}$ to be recognized by the ADC.
D0	2	3-state data output, bit 1 (LSB)
D1	3	3-state data output, bit 2
D2	4	3-state data output, bit 3
D3	5	3-state data output, bit 4
D4	14	3-state data output, bit 5
D5	15	3-state data output, bit 6
D6	16	3-state data output, bit 7
D7	17	3-state data output, bit 8 (MSB)
GND	10	Ground
$\overline{INT}$	9	In the write-read mode, the interrupt output, $\overline{INT}$, going low indicates that the internal count-down delay time, $t_{d(int)}$, is complete and the data result is in the output latch. $t_{d(int)}$ is typically 800 ns starting after the rising edge of the $\overline{WR}$ input (see operating characteristics and Figure 3). If $\overline{RD}$ goes low prior to the end of $t_{d(int)}$, $\overline{INT}$ goes low at the end of t_{dRIL} and the conversion results are available sooner (see Figure 2). $\overline{INT}$ is reset by the rising edge of either $\overline{RD}$ or $\overline{CS}$.
MODE	7	Mode-selection input. It is internally tied to GND through a 50-μA current source, which acts like a pull-down resistor. read mode: Occurs when this input is low. write-read mode: Occurs when this input is high.
NC	19	No internal connection
$\overline{OFLW}$	18	Normally the $\overline{OFLW}$ output is a logical high. However, if the analog input is higher than the V_{ref+}, $\overline{OFLW}$ will be low at the end of conversion. It can be used to cascade 2 or more devices to improve resolution (9 or 10-bits).
$\overline{RD}$	8	In the write-read mode with $\overline{CS}$ low, the 3-state data outpus D0 through D7 are activated when $\overline{RD}$ goes low. $\overline{RD}$ can also be used to increase the conversion speed by reading data prior to the end of the internal count-down delay time. As a result, the data transferred to the output latch is latched after the falling edge of $\overline{RD}$. In the read mode with $\overline{CS}$ low, the conversion starts with $\overline{RD}$ going low. $\overline{RD}$ also enables the 3-state data outputs upon completion of the conversion. The RDY output going into the high-impedance state and $\overline{INT}$ going low indicates completion of the conversion.
REF –	11	This input voltage is placed on the bottom of the resistor ladder.
REF +	12	This input voltage is placed on the top of the resistor ladder.
V_{CC}	20	Power supply voltage
$\overline{WR}$/RDY	6	In the write-read mode with $\overline{CS}$ low, the conversion is started on the falling edge of the $\overline{WR}$ input signal. The result of the conversion is strobed into the output latch after the internal count-down delay time, $t_{d(int)}$, provided that the $\overline{RD}$ input does not go low prior to this time. $t_{d(int)}$ is approximately 800 ns. In the READ mode, RDY (an open-drain output) will go low after the falling edge of $\overline{CS}$, and will go into the high-impedance state when the conversion is strobed into the output latch. It is used to simplify the interface to a microprocessor system.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

	TLC0820_C ADC0820_C	TLC0820_I ADC0820_CI	TLC0820_M	UNIT
Supply voltage, V_{CC} (see Note 1)	10	10	10	V
Input voltage range, all inputs (see Note 1)	−0.2 to V_{CC}+0.2	−0.2 to V_{CC}+0.2	−0.2 to V_{CC}+0.2	V
Output voltage range, all outputs (see Note 1)	−0.2 to V_{CC}+0.2	−0.2 to V_{CC}+0.2	−0.2 to V_{CC}+0.2	V
Operating free-air temperature range	0 to 70	−40 to 85	−55 to 125	°C
Storage temperature range	−65 to 150	−65 to 150	−65 to 150	°C
Case temperature for 60 seconds: FK package			260	°C
Case temperature for 10 seconds: FN package	260	260		°C
Lead temperature 1,6 mm (1/16 inch) from case for 60 seconds: J package			300	°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds: DW or N package	260	260	260	°C

NOTE 1: All voltages are with respect to network GND.

recommended operating conditions

			TLC0820_C ADC0820_C			TLC0820_I ADC0820_CI			TLC0820_M			UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	MIN	NOM	MAX	
Supply voltage, V_{CC}			4.5	5	8	4.5	5	8	4.5	5	8	V
Analog input voltage			−1.0		V_{CC}+0.1	−0.1		V_{CC}+0.1	−0.1		V_{CC}+0.1	V
Positive reference voltage, V_{REF+}			V_{REF-}		V_{CC}	V_{REF-}		V_{CC}	V_{REF-}		V_{CC}	V
Negative reference voltage, V_{REF-}			GND		V_{REF+}	GND		V_{REF+}	GND		V_{REF+}	V
High-level input voltage, V_{IH}	V_{CC} = 4.75 V to 5.25 V	$\overline{CS}$, $\overline{WR}$/RDY, $\overline{RD}$	2			2			2			V
		MODE	3.5			3.5			3.5			V
Low-level input voltage, V_{IL}	V_{CC} = 4.75 V to 5.25 V	$\overline{CS}$, $\overline{WR}$/RDY, $\overline{RD}$			0.8			0.8			0.8	V
		MODE			1.5			1.5			1.5	V
Delay to next conversion $t_{d(NC)}$ (see Figures 1, 2, 3, and 4)			500			500			500			ns
Delay time from $\overline{WR}$ to $\overline{RD}$ in write-read mode, t_{dwR} (see Figure 2)			0.4			0.4			0.4			µs
Write-pulse duration in write-read mode, (t_{dwR}) (see Figures 2, 3, and 4)			0.5		50	0.5		50	0.5		50	µs
Operating free-air temperature, T_A			0		70	– 40		85	−55		125	5C

electrical characteristics at specified operating free-air temperature, V_{CC} = 5 V (unless otherwise noted)

PARAMETER			TEST CONDITIONS	T_A†	MIN	TYP‡	MAX	UNIT
V_{OH}	High-level output voltage	Any D, $\overline{INT}$, or $\overline{OFLW}$	V_{CC} = 4.75 V, I_{OH} = –360 µA	Full range	2.4			V
			V_{CC} = 4.75 V, I_{OH} = –10 µA	Full range	4.5			
				25°C	4.6			
V_{OL}	Low-level output voltage	Any D, $\overline{OFLW}$, $\overline{INT}$, or $\overline{WR}$/RDY	V_{CC} = 5.25 V, I_{OL} = 1.6 mA	Full range			0.4	V
				25°C			0.34	
I_{IH}	High-level input current	$\overline{CS}$ or $\overline{RD}$	V_{IH} = 5 V	Full range		0.005	1	µA
		$\overline{WR}$/RDY		Full range			3	
				25°C		0.1	0.3	
		MODE		Full range			200	
				25°C		50	170	
I_{IL}	Low-level input current	$\overline{CS}$, $\overline{WR}$/RDY, $\overline{RD}$, or MODE	V_{IL} = 0	Full range		–0.005	–1	µA
I_{OZ}	Off-state (high-impedance state) output current	Any D or $\overline{WR}$/RDY	V_O = 5 V	Full range			3	µA
				25°C		0.1	0.3	
			V_O = 0	Full range			–3	
				25°C		–0.1	–0.3	
I_I	Analog input current		$\overline{CS}$ at 5 V, V_I = 5 V	Full range			3	µA
				25°C			0.3	
			$\overline{CS}$ at 5 V, V_I = 0	Full range			–3	
				25°C			–0.3	
I_{OS}	Short-circuit output current	Any D, $\overline{OFLW}$, $\overline{INT}$, or $\overline{WR}$/RDY	V_O = 5 V	Full range	7			mA
				25°C	8.4	14		
		Any D or $\overline{OFLW}$	V_O = 0	Full range	–6			
				25°C	–7.2	–12		
		INT		Full range	–4.5			
				25°C	– 5.3	–9		
R_{ref}	Reference resistance			Full range	1.25		6	kΩ
				25°C	1.4	2.3	5.3	
I_{CC}	Supply current		$\overline{CS}$, $\overline{WR}$/RDY, and $\overline{RD}$ at 0 V	Full range			15	mA
				25°C		7.5	13	
C_i	Input capacitance	Any digital		Full range		5		pF
		ANLG IN				45		
C_o	Output capacitance	Any digital		Full range			5	pF

† Full range is as apecified in recommended operating conditions.
‡ All typical values are at T_A = 25°C.

operating characteristics, V_{CC} = 5 V, V_{REF+} = 5 V, V_{REF-} = 0, $t_r = t_f$ = 20 ns, T_A = 25°C (unless otherwise noted)

PARAMETER		TEST CONDITIONS†		TLC0820B ADC0820B			TLC0820A ADC0820C			UNIT
				MIN	TYP	MAX	MIN	TYP	MAX	
k_{SVS}	Supply voltage sensitivity	V_{CC} = 5 V ±5%, T_A = MIN to MAX			±1/16	±1/4		±1/16	±1/4	LSB
	Total unadjusted error‡	MODE at 0 V, T_A = MIN to MAX				1/2			1	LSB
t_{convR}	Read mode conversion time	MODE at 0 V, See Figure 1			1.6	2.5		1.6	2.5	µs
$t_{d(int)}$	Internal countdown delay time	MODE at 5V, C_L = 50 pF, See Figures 3 and 4			800	1300		800	1300	ns
t_{aR}	Access time from $\overline{RD}$↓	MODE at 0 V, See Figure 1			t_{convR} +20	t_{convR} +50		t_{convR} +20	t_{convR} +50	ns
t_{aR1}	Access time from $\overline{RD}$↓	MODE at 5 V, $t_{dWR} < t_{d(int)}$, See Figure 2	C_L = 15 pF		190	280		190	280	ns
			C_L = 100 pF		210	320		210	320	
t_{aR2}	Access time from $\overline{RD}$↓	MODE at 5 V, $t_{dWR} > t_{d(int)}$, See Figure 3	C_L = 15 pF		70	120		70	120	ns
			C_L = 100 pF		90	150		90	150	
t_{aINT}	Access time from $\overline{INT}$↓	MODE at 5 V, See Figure 4			20	50		20	50	ns
t_{dis}	Disable time from $\overline{RD}$↑	R_L = 1 kΩ, C_L = 10 pF, See Figures 1, 2, 3, and 5			70	95		70	95	ns
t_{dRDY}	Delay time from $\overline{CS}$ to RDY	MODE at 0 V, C_L = 50 pF, See Figure 1			50	100		50	100	ns
t_{dRIH}	Delay time from $\overline{RD}$↑ to $\overline{INT}$↑	C_L = 50 pF, See Figures 1, 2, and 3			125	225		125	225	ns
t_{dRIL}	Delay time from $\overline{RD}$↓ to $\overline{INT}$↓	MODE at 5 V, $t_{dWR} < t_{d(int)}$, See Figure 2			200	290		200	290	ns
t_{dWIH}	Delay time from $\overline{WR}$↑ to $\overline{INT}$↑	MODE at 5 V, C_L = 50 pF, See Figure 4			175	270		175	270	ns
	Slew rate tracking				0.1			0.1		ns

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.
‡ Total unadjusted error includes offset, full-scale, and linearity errors.

PARAMETER MEASUREMENT INFORMATION

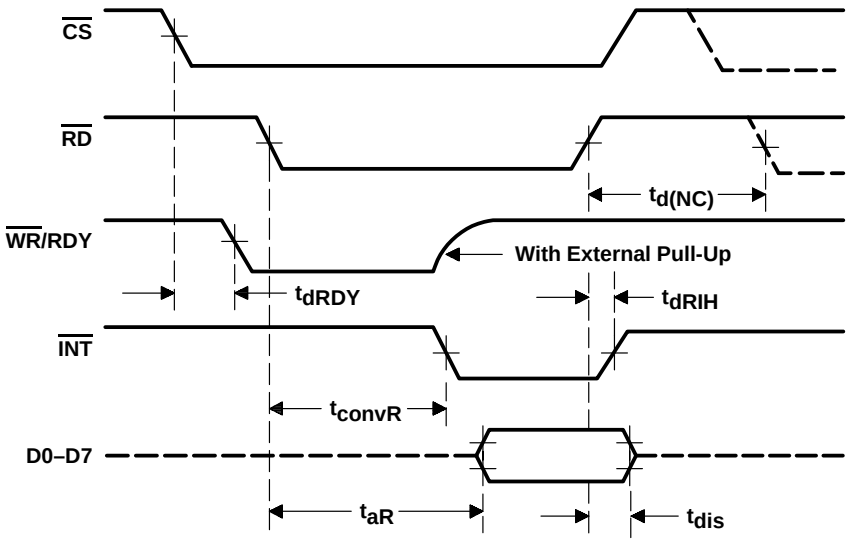


Figure 1. Read Mode Waveforms (Mode Pin Low)

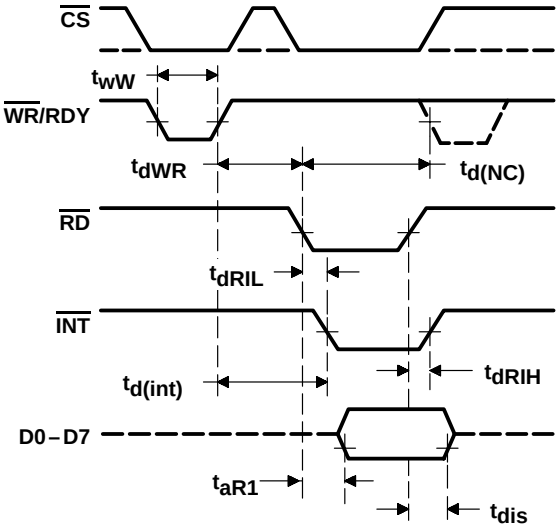


Figure 2. Write-Read Mode Waveforms [Mode Pin High and $t_{dWR} < t_{d(int)}$]

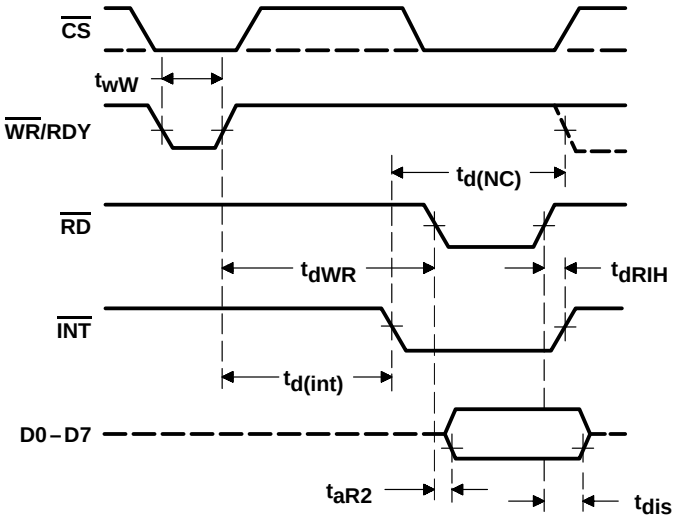


Figure 3. Write-Read Waveforms [Mode Pin High and $t_{dWR} > t_{d(int)}$]

PARAMETER MEASUREMENT INFORMATION

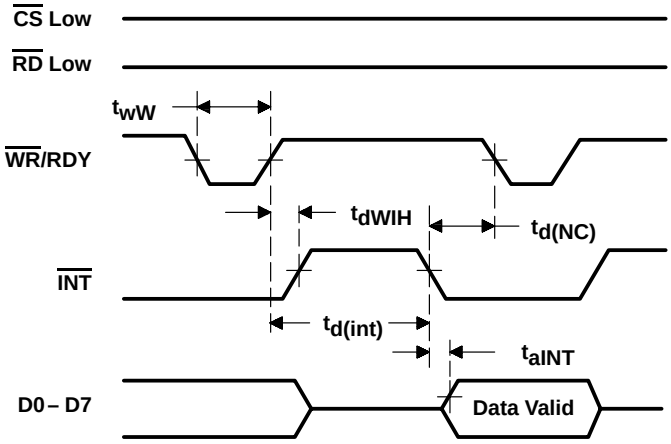


Figure 4. Write-Read Mode Waveforms (Stand-Alone Operation, MODE High, and RD Low)

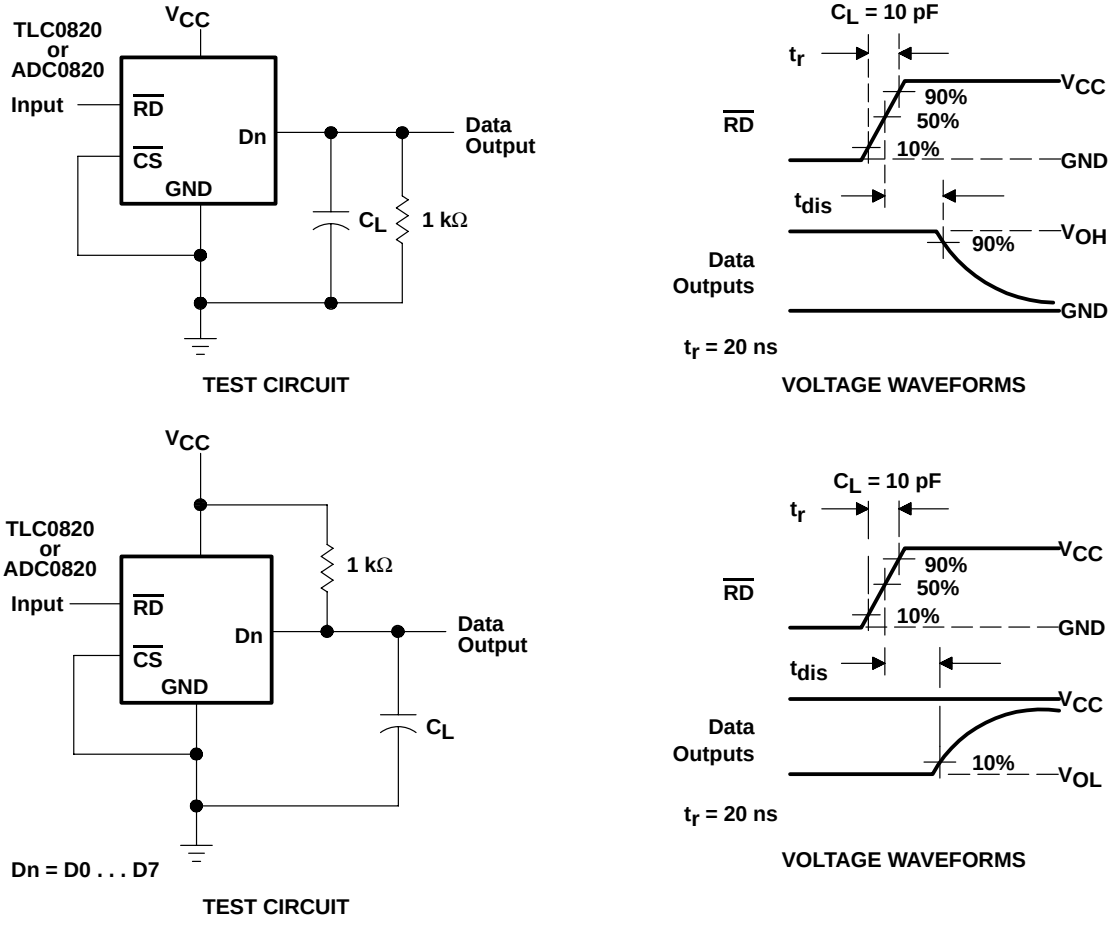


Figure 5. Test Circuit and Voltage Waveforms

PRINCIPLES OF OPERATION

The TLC0820A, TLC0820B, ADC0820B, and ADC0820C each employ a combination of sampled-data comparator techniques and "flash" techniques common to many high-speed converters. Two 4-bit "flash" analog-to-digital conversions are used to give a full 8-bit output.

The recommended analog input voltage range for conversion is –0.1 V to V_{CC} + 0.1 V. Analog input signals that are less than V_{REF-} + 1/2 LSB or greater than V_{REF+} – 1/2 LSB convert to 00000000 or 11111111, respectively. The reference inputs are fully differential with common-mode limits defined by the supply rails. The reference input values define the full-scale range of the analog input. This allows the gain of the ADC to be varied for ratiometric conversion by changing the V_{REF+} and V_{REF-} voltages.

The device operates in two modes, read (only) and write-read, which are selected by MODE. The converter is set to the read (only) mode when MODE is low. In the read mode, the $\overline{WR}$/RDY pin is used as an output and is referred to as the ready pin. In this mode, a low on the ready pin while $\overline{CS}$ is low indicates that the device is busy. Conversion starts on the failing edge of $\overline{RD}$ and is completed no more than 2.5 µs later when $\overline{INT}$ falls and the ready pin returns to a high-impedance state. Data outputs also change from high-impedance to active states at this time. After the data is read, $\overline{RD}$ is taken high, $\overline{INT}$ returns high, and the data outputs return to their high-impedance states.

The converter is set to the write-read mode when MODE is high and $\overline{WR}$/RDY is referred to as the write pin. Taking $\overline{CS}$ and the write pin low selects the converter and initiates measurement of the input signal. Approximately 600 ns after the write pin returns high, the conversion is completed. Conversion starts on the rising edge of $\overline{WR}$/RDY in the write-read mode.

The high-order 4-bit "flash" ADC measures the input by means of 16 comparators operating simultaneously. A high precision 4-bit DAC then generates a discrete analog voltage from the result of that conversion. After a time delay, a second bank of comparators does a low-order conversion on the analog difference between the input level and the high-order DAC output. The results from each of these conversions enter an 8-bit latch and are output to the 3-state buffers on the failing edge of $\overline{RD}$.

APPLICATION INFORMATION

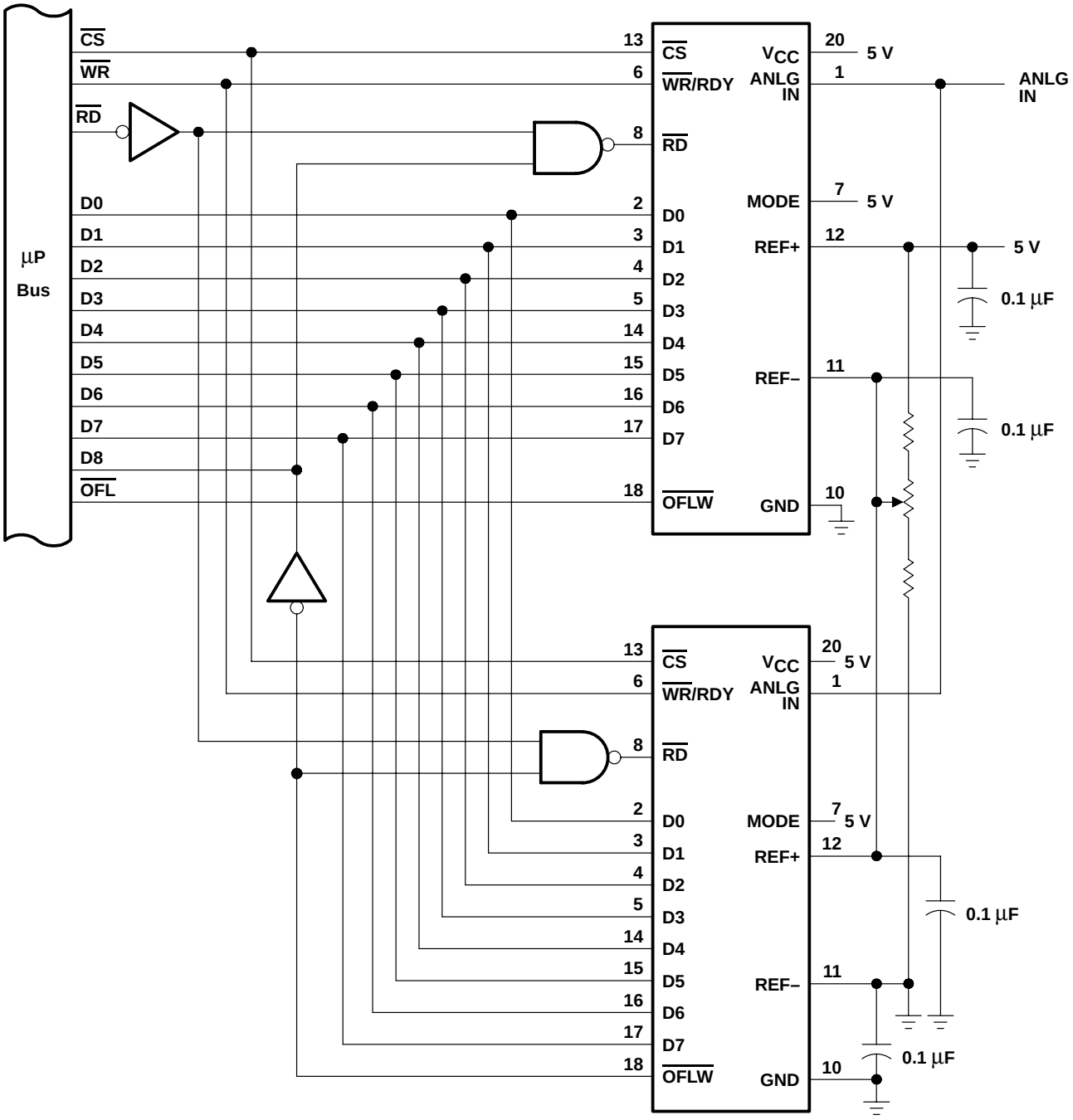


Figure 6. Configuration for 9-Bit Resolution

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